

Rev	Description	Appd.	Date
0	initial release	lag	12-20-00

Notes:

1.0 Orientations

- 1.1 Wafer surface is normal to  $\langle Z \rangle \pm 0.5^\circ$
- 1.2 Flats
  - 1.2.1 Primary flat is normal to  $\langle -Y \rangle \pm 0.5^\circ$ .
  - 1.2.2 Secondary flat is normal to  $\langle -X \rangle \pm 0.5^\circ$ .

2.0 Edge

- 1.1 All edges rounded with  $R0.57 \pm 0.08\text{mm}$ .
- 1.2 No chips more than 0.5mm in penetration and 1.0mm in length.

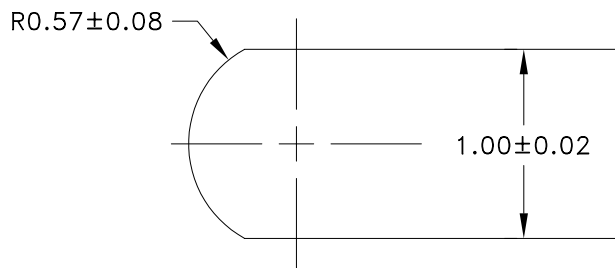
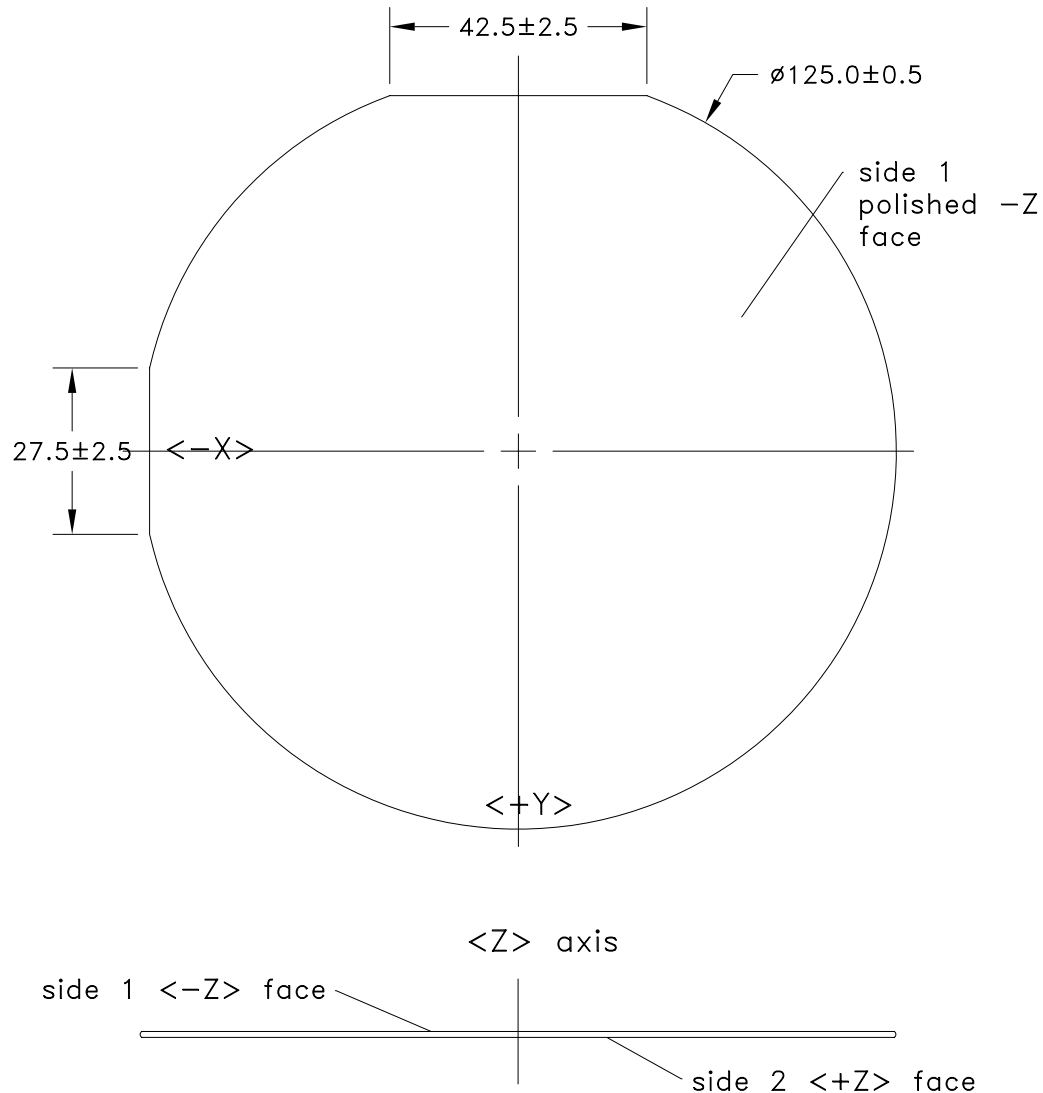
3.0 Surfaces

- 3.1 Side 1  $\langle -Z \rangle$  face  
Polished 10-5 scratch-dig with 1mm edge exclusion. Inspected with reflected light and unaided eye.
- 3.2 Side 2  $\langle +Z \rangle$  face  
Polished 60-30 scratch-dig with 1mm edge exclusion. Inspected with reflected light and unaided eye.

4.0 Flatness


- 4.1 Warp  $< 50\mu\text{m}$ .
- 4.2 TTV  $< 25\mu\text{m}$ .

**For Reference Only**



Wafer Edge Detail, 25X

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Material: Lithium Niobate	DR. Igordon	12-20-00	 <b>Crystal Technology, Inc.</b> An EPCOS Company
Unless otherwise specified, dimensions in mm	CHK.		
Tolerances			Title: LNIO 125 $\phi$ x 1.0mm, $\langle -Z \rangle$ Po/Po, $-Y$ FLT
Inches	Millimeters	Wafer Code:	
.X $\pm$ 0.1	X $\pm$ 0.5		
.XX $\pm$ 0.01	.X $\pm$ 0.25	Customer Approval:	
.XXX $\pm$ 0.005	.XX $\pm$ 0.1		Size: A Dwg. No: 97-02641-01 Rev: A
.XXXX $\pm$ 0.0020	.XXX $\pm$ 0.05		Scale: 0.8:1 Sheet 1 of 1
Angles $\pm$ 0.5°	DO NOT SCALE DRAWING		